

Fast & Flexible Mounter

DECAN S1



Next Generation Medium Speed Chip Mounter

DECAN S1

- Improves actual productivity
- Improves placement quality
- Reduces loss rate

As a chip mounter which was developed focusing on **visible improvements**, one of the three major indexes, this chip mounter provides the optimum productivity necessary for batch production.

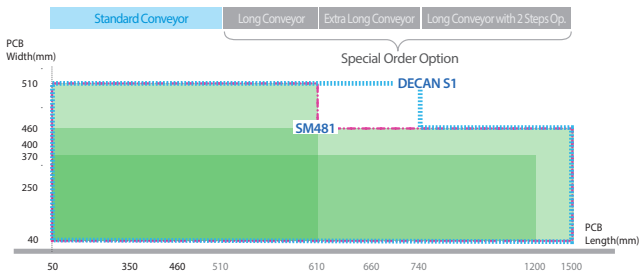
Specifications

Model Name		DECAN S1	
Alignment		Fly Camera + Fix Camera	
The number of spindles		10 spindles x 1 Gantry	
Placement Speed		47,000 CPH (Optimum)	
Placement Accuracy	Chip	±28µm @ Cpk≥ 1.0	
	IC	±35µm @ Cpk≥ 1.0	
Component Range	Fly Camera	03015 ~ □ 16mm	
	Fix Camera	~ □ 42mm (Standard) □ 42mm ~ □ 55mm (MFOV) L55mm ~ L75mm Connector (MFOV)	
	Max. Height	10mm (Fly), 15mm (Fix)	
PCB Size (mm)	Min.	50(L) x 40(W)	
	Max.	Standard	510(L) x 510(W)
		Option	~ Max. 1,500(L) x 460(W)
PCB Thickness (mm)		0.38 ~ 4.2	
Feeder Capacity (8mm standard)	Standard	60ea / 56ea (Fixed feederbase / Docking Cart)	
	Option	120ea / 112ea (Fixed feederbase / Docking Cart)	
Utility	Power	3Phase AC200 / 208 / 220 / 240 / 380 / 415V Max. 3.5kVA	
	Air Consumption	5.0~7.0kgf/cm ² 50Nℓ/min (Vacuum Pump)	
Weight (kg)		Approx. 1,600	
External Dimension (mm)		1,430(L) x 1,740(D) x 1,485(H)	

Highest Performance among Chip Mounters of the Same Class

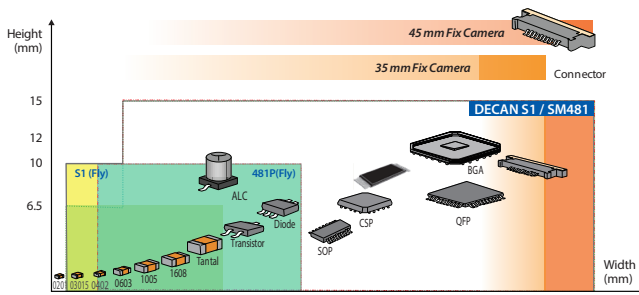
Highest Applicability of Medium Speed Chip Mounters to PCBs

- 510 x 510mm (standard) / 1500 x 460mm (option)
- Possible to produce PCBs up to 1,500mm(L) x 460mm(W) in size



Expands the Component Recognition Range with a High Pixel Camera

- The fly camera can recognize all chips of 03015 ~ □16mm



Improves Simultaneous Pickup Rate

- Arranges pocket positions automatically through communication between the machine and feeder

Improves the Placement Speed of an Odd-Shape Component

- Increases speed by approximately 25% by optimizing the fix camera recognized motion sequence

Increased Convenience of Operation

Reduces the Teaching Time of a Large Odd-shape Component

- Expanded FOV of Fiducial Camera: □7.5mm → □12mm
- Reduces the time to teach the component pickup/placement point and improves the convenience of teaching

Maintains the Pickup Coordinate of the Common Feeder

- When changing a model, reduces the model changing time by succeeding the pickup information of a similar model

Unifies the Chip Component Lighting Level

- By setting the same lighting value collectively, minimizes the lighting changing time, removes the productivity deviation by machine and improves the convenience of part DB management

* Since this is under development, it will be available for Auto Maintenance function in December 2018 and Multi-Vendor function in October 2018.

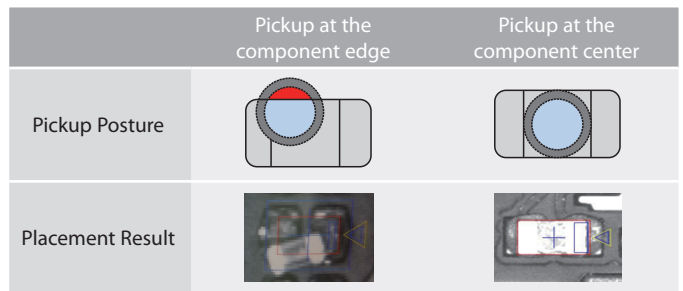
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• The dimensions and product specifications in this catalog may be changed without prior notice. The dimensions, product specifications and values in this catalog are actual values measured under conditions designated by our company.
• The above items may differ depending on actual operating conditions. For the details related to options, please contact the person responsible for sales.

Places Microchips Stably

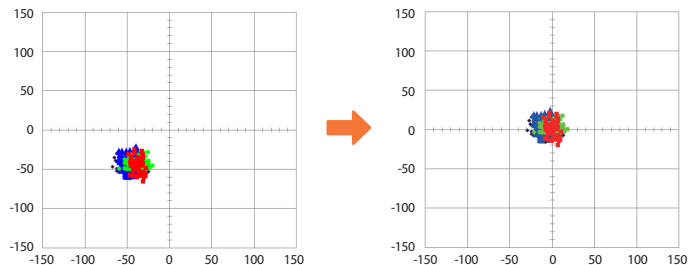
Recognizes the Nozzle Center

- Improves the microchip loss rate and placement quality by preventing the occurrence of air leaks



Run Time Calibration

- Maintains placement accuracy by performing automatic calibration during production



Auto Maintenance Prevents Pickup Error and Maintains Placement Quality *

- Measures pneumatic pressure and flow rate of the nozzle and shaft
- Removes foreign materials on the nozzle and shaft by high pressure air blast

Support of Multi-vendor Component *

- It's possible to manage the same components supplied by two suppliers in one part name, so it's Possible to perform production continuously without changing the PCB program for the components supplied by different vendors

Teaches Large-sized Components Easily (Panoramic View)

- Performs split-recognition of a large-sized component that is out of the camera recognition range (FOV) and merges split component images into a single image before displaying.
- Easily teaches the pickup/placement position of a large-sized component

